

EFEM Platform



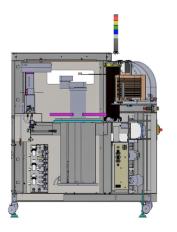
Our **EFEM Platform** can be customized to suit your application's cleanliness, handling technique, throughput, and form-factor specifications. From design to manufacturing, this single platform offers the needed hardware, software, vision, optics design, sub-micron metrology, environmental control and materials handling for varying complexity and precision requirements.

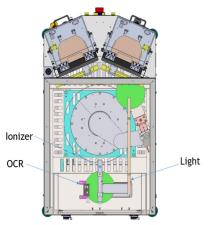
EFEM Platform

An Ultra-Clean, Reliable Platform for Wafer Handling

Get to Market Faster:

- Adaptable to different wafer technologies including film-frame carrier strategies, taiko wafers, thin/thick wafers, bonded wafers, non-flat wafers / wafers with 3D structures, and glass wafers
- •High MTBF
- Mini-environment for contamination
- ESD charge control options
- Vacuum and low contamination integration capabilities
- Configurable layout for process simplication and/or footprint/ form factor optimization
- High accuracy aligner systems to 10 µm accuracy
- Integrated vibration isolation capabilities





	EFEM Platform
Environmental	Mini-Environment for up to ISO Class 1 Operation Temperature Control Electrostatic Charge Reduction
Wafer Handling	 Wafer Size: 300, 200, 150, 100 Accommodates Various Thicknesses and Warped Wafers Varying Substrate Materials (Glass, Silicon, Silicon Carbide, Germanium) End Effectors or Various Gripping Technologies (Edge, Vacuum, Bernoulli) Wafer Flipping Industry Standard SMIF and FOUP Load Ports (one to four interfaces) Accommodates Special Modules such as High-Precision Aligners
Robotics	Single and Dual Arm 3-Axis and 4-Axis
Vision & Optical	Barcode Readers Fiducial Recognition OCR Defect Analysis and Characterization Flatness Analysis
Software Requirements & Features	Standard 300 mm & 200 mm SEMI Compliant Libraries Interfacing Protocols to Host Controller in Standard EFEM SMEMA & SECS/GEM Interfaces Data Management and Tracking Capabilities SEMI E95 Compliance for Human Machine Interface (HMI) Wafer Mapping

